ONYX & DRS

Dipping Kit for Solder Paste or Flux - Part #FASET1

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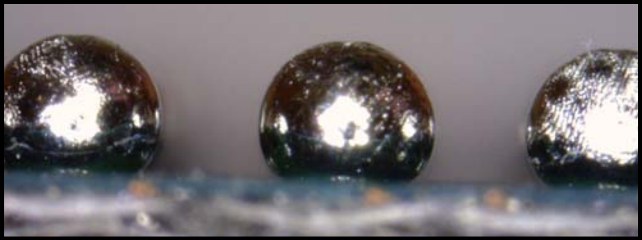


Bare Solder Spheres

Dipped Solder Spheres

SUPERIOR TO APPLYING PASTE VIA COMPONENT OR BOARD STENCILS

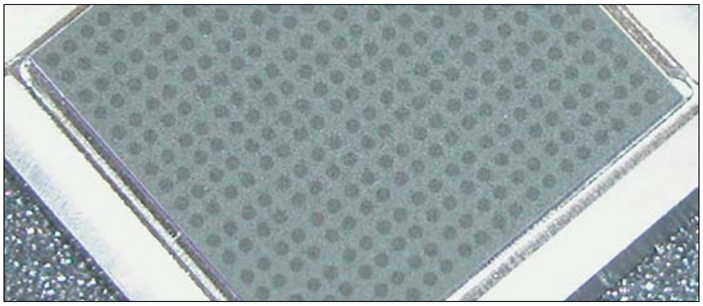
- Easier Process and Less Operator Involvement than Stencils (Consistent Results)
- No Component or Board/Pad Coplanarity Preparation Issues
- No Adjacent Interference Issues
- Excellent for Extremely Fine Pitch, Sphere or Leaded Size Components
- One Set of Dipping Pedestals Replaces Dozens of Custom Component Stencils

Dippable solder paste is a very low viscosity, high flux content solder paste, giving it a consistency like a thick latex paint.

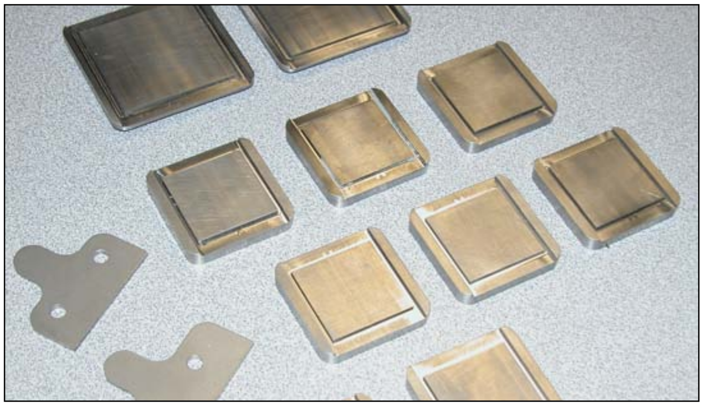
Utilizing the replacement nozzle, the BGA or leaded device is dipped into a defined depth of this solder paste using the correct pedestal (depth = approx.1/2 the sphere diameter for BGAs) and the paste uniformly coats the solder sphere surfaces.

The dipped component is then aligned and placed. As the board and part are heated the paste reflows together with the solder sphere for a high quality solder joint.

Uniform solder and flux volume per joint results in consistent process control.



Paste Imprint of Dipped BGA



Included with each Kit:

- Qty 8 - 30x30mm trays of depths: .002″, .004″, .006″, .008″, .010″, .012″, .015″. (P/N FA30X30-**)
- Qty 2 – 45x45mm trays of depths: .008″, .012″. (P/N FA45X45-**)
- Squeegee blades FAB1750 & FAB2250
- Carrying case

- Individual or custom dipping trays can also be ordered to any size and depth.

- For a quote contact Air-Vac at 203-888-9900 or rework.sales@air-vac-eng.com